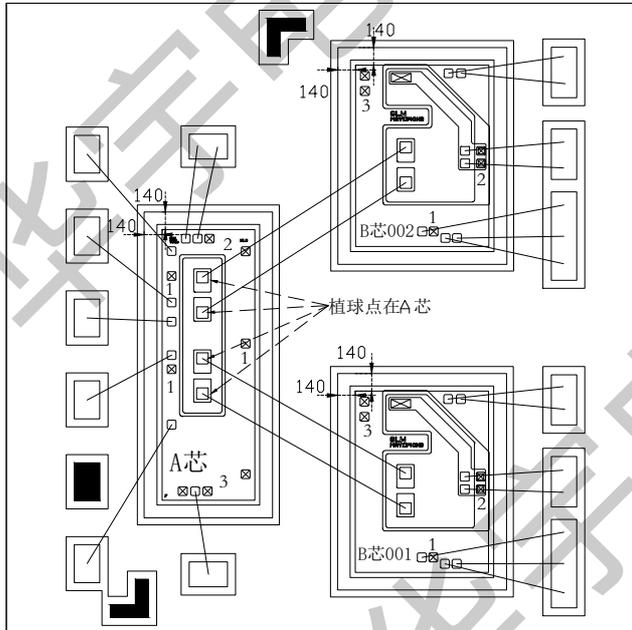
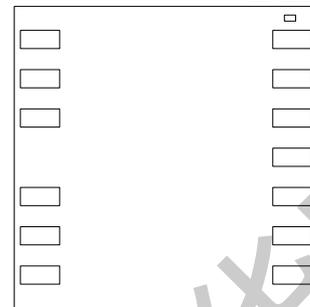


| | | | | | | | |
|---|---------------------------|---------------------|-------------------------------|---------------------------------|----------------------------------|--|-----------------------|
|  池州华宇电子科技股份有限公司 CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD 焊线图纸 Bonding Diagram | | | 客户代码 Customer No. | 线图号 Drawing No. | 页码 Page 1/2 | | |
| 产品名称 Product Type | | | 封装外型 PKG Type | | LGA13L(5×5×0.8-P0.65) | | |
| 焊线种类 Wire Type | 焊线直径(μm) Wire Diameter | 焊线根数 NO. of wire | 焊线总长(μm) Total wire length | 最长线长(μm) Longest wire length | 最短线长(μm) Shortest wire length | 塑封料型号(绿色环保) Compound Type (Green) | 基板编码 Substrate No. |
| 金丝 Au | 25 | | | 1905 | 668 | 首选(Preferred): KE-G1250 备选(Optional): | |
| 客户图号 Customer drawing NO. | | | | | | | |

PIN1

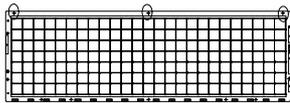


PIN1



底面PIN示意图

框架传送方向(装片):
L/F Direction (D/A): 上侧三个圆孔



实物图:
Chip photo:

特殊说明 Special Instructions:

DB注意:

1. 装片位置公差为主30um;
2. 控制溢胶, 为WB预留焊线位置; 避免溢胶到finger.
3. 以随工单要求按顺序装片, 如: 先装A芯片, 装B芯001和B芯002时, 必须先装在A芯片的基板, 反之先装B芯001和B芯002时, 装A芯片时B芯001和B芯002已经装片.

WB注意:

数字为不打线 ad点个数.

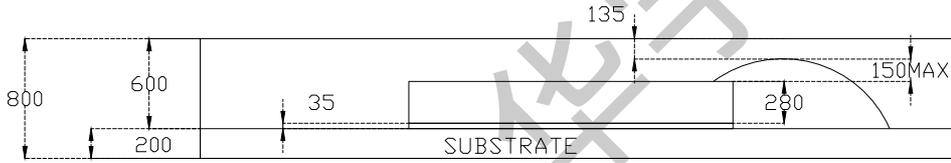
| 说明 Instructions | 粘片胶类型 epoxy type | 芯片名称 Die name | 芯片尺寸 Die Size | 最小焊盘尺寸 Min BPO (μm²) | 最小焊盘间距 Min BPP(μm) | 锡垫厚度(μm) Pad Thickness | 焊盘下是否有电路 Circuit under Pad | 划片道宽度 Street line (μm) | 晶圆尺寸 Wafer Size | 是否是 Low-K Epoxy-2 | 减薄厚度 (μm) Wafer Thickness |
|--------------------|-------------------------------|------------------|-------------------------------------|-------------------------|-----------------------|---------------------------|-------------------------------|---------------------------|----------------------------------|-------------------------|---------------------------------|
| A芯: DIE A | 导电胶 (conductivity) 6389 | | 730*2148(μm²) 28.74*84.57(mil²) | 70*70 | 93 | 3.5 | 是/YES | 80 | 8 | 否/NO | 280 客户要求 |
| B芯: DIE B | 导电胶 (conductivity) 6389 | | 1050*1440(μm²) 41.34*56.70(mil²) | 70*70 | 100 | 3.5 | 是/YES | 80 | 8 | 否/NO | 280 客户要求 |
| 拟制 Prepared by | | | 制图日期 Create Date | | | | 生效日期 Effective Date | | 客户确认签字/盖章: Customer Signature | | |
| 研发审核 R&d check | | | 产品工程审核 Product engineering check | | | | 批准 Approved by | | | | |

*温馨提示: 图纸为产品下线的唯一依据, 请您认真确认, 我司依据您回签后的图纸生产, 如图纸错误会产生不可估量损失, 谢谢!

*warm tips: the drawing is the only basis for the production of the product. Please confirm it carefully. Our company will produce the drawings according to the drawings you have signed back, such as drawing mistakes, which will produce incalculable loss. Thank you



| | | | | |
|----------------------|--|--------------------|-----------------------|----------------|
| 客户代码 Customer No. | | 线图号 Drawing No. | | 页码 Page 2/2 |
| 产品名称 Product Type | | 封装外型 PKG Type | LGA13L(5×5×0.8-P0.65) | |



| | | | | | | |
|-------------------|--|-------------------------------------|--|------------------------|--|----------------------------------|
| 拟制 Prepared by | | 制图日期 Create Date | | 生效日期 Effective Date | | 客户确认签字/盖章: Customer Signature |
| 研发审核 R&d check | | 产品工程审核 Product engineering check | | 批准 Approved by | | |

*温馨提示: 图纸为产品下线生产的唯一依据, 请您认真确认, 我司依据您回签后的图纸生产, 如图纸错误会产生不可估量损失, 谢谢!
*warm tips: the drawing is the only basis for the production of the product. Please confirm it carefully. Our company will produce the drawings according to the drawings you have signed back, such as drawing mistakes, which will produce incestimable loss. Thank you